

iMAPS New England – 47th Symposium & Expo

**The Largest Regional Symposium Dedicated to
Microelectronics, Assembly and Packaging
Boxboro Regency Hotel & Conference Center
Boxborough, Massachusetts**

May 12, 2020

EarlyBird II Exhibitor Registration is Open!!

30 Companies Have Already Registered...!!

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The Technical Program is Being Assembled NOW



Call for Papers & Posters

- 2D-3D & Beyond
- Medical Device Packaging
- RF & Microwave Innovative Technologies
- Wire & Die Bonding, Flip Chip, Bumping, TSV
- SMT & Electronics Assembly-Packaging
- Thermal Management Materials & Designs
- Military, Defense & Space Microelectronics
- High Temperature Electronics
- MEMS Sensors & Nano Technology
- Wearables - Consumer Applications
- Advanced Semiconductor Packaging
- Printed Electronics - Additive Manufacturing
- Nanoelectronic - Optoelectronic Packaging
- New & Emerging Materials-Technologies

Please e-mail your 250 word abstract to: imapsne-abstracts@imapsne.org

Dmitry Marchenko, Chapter President



Deadline for Submission – December 31, 2019

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